

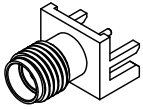
MATERIALS AND FINISHES

BODY BRASS  
PLATED GOLD

CENTER CONTACT BERYLLIUM COPPER  
PLATED GOLD

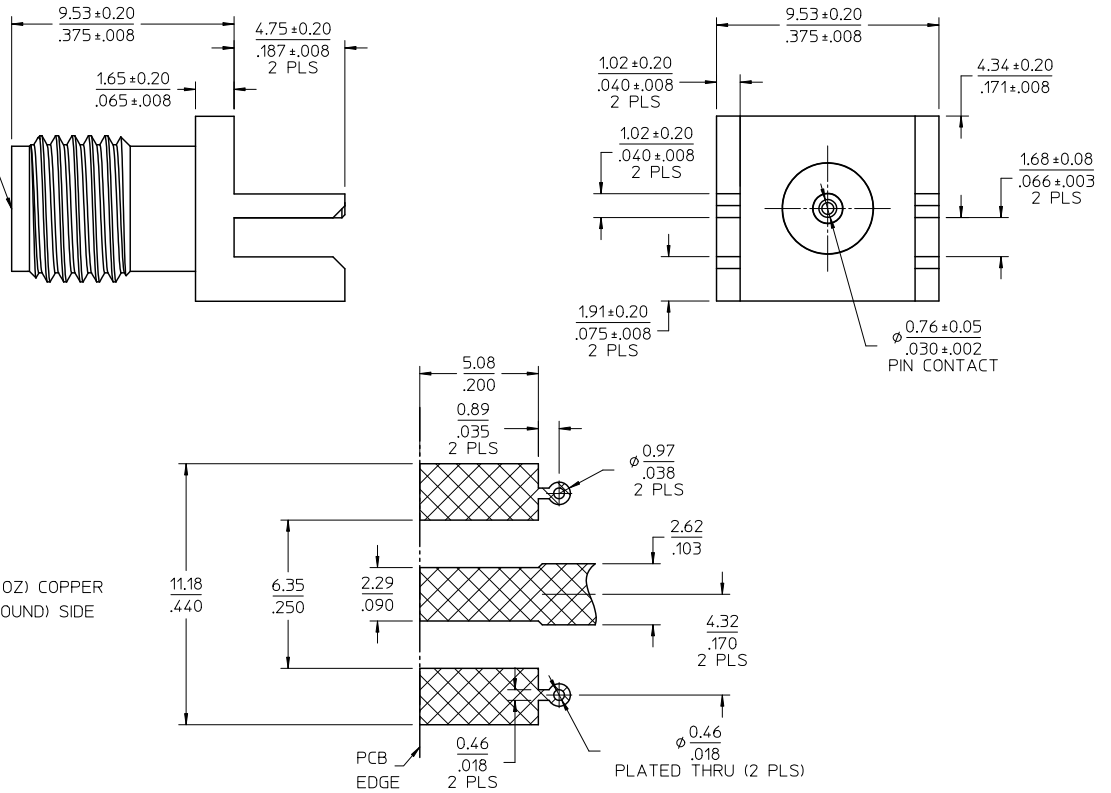
INSULATOR TEFLON

SMA JACK  
INTERFACE



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)  
BOARD THICKNESS: 1.57(.062)  
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER  
ON BOTTOM (GROUND) SIDE



73251-1152	TRAY (20 PIECES)
73251-1151	ONE PIECE 73251-1150 PER BAG
73251-1150	TRAY (80 PIECES)
PART NO.	PACKAGING

PS-89675-2820	ELEC/MECH PERFORMANCE
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: CLARIFIED BAGGING. EC NO: URF2010-0369 DRW: ROBERTSON 2009/12/18 CHK: SSS 2009/12/18 APPR: JWIENER 2009/12/18 A5	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		4 PLACES ±--- ±---	mm	INCH	MM/IN	METRIC	☉	
		3 PLACES ±--- ±---	DRAWN BY TEF		DATE 2002/06/27	TITLE SMA JACK, EDGE MOUNT		
		2 PLACES ±--- ±---	CHECKED BY SSS		DATE 2002/06/27	50 OHMS, EWR-1764		
1 PLACE ±--- ±---	APPROVED BY GMH		DATE 2002/06/27	MATERIAL NO. SD-73251-115			SHEET NO. 1 OF 1	
ANGULAR ± 2 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SD-73251-115				SHEET NO. 1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								